



## Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-03-05
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty statement**

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**Legal statement**

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32U535CET6	715B*455XXXY	A	998Z	2024-03-05
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	178	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFP	7x7	48	Gull wing	
Comment	Package : 5B LQFP 48 7x7x1.4 1 0110596			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-23rd January 2024				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	0			

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	715B*455XXXY		178.2442		6000000.0	1000000.0	
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die or dies	M-011 Other inorganic materials	10.134	mg	supplier	die	Silicon (Si)	7440-21-3		9.739	mg	961028	54640	
				supplier	metallization	Aluminium (Al)	7429-90-5		0.044	mg	4300	244	
				supplier	metallization	Copper (Cu)	7440-50-8		0.130	mg	12832	730	
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	68	4	
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.022	mg	2184	124	
				supplier	metallization	Titanium (Ti)	7440-32-6		0.006	mg	546	31	
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	68	4	
				supplier	Passivation	Silicon Nitride	12033-89-6		0.031	mg	3071	175	
				supplier	Passivation	Silicon Oxide	7631-86-9		0.161	mg	15903	904	
				supplier	Metals	Silver	7440-22-4		1.125	mg	815000	6310	
Glue epoxy (3230)	M-011 Other inorganic materials	1.380	mg	supplier	Plastics/polymers	2,2'-(Methylenebis(phenyleneoxymethylene))bis	39817-09-9		0.041	mg	30000	232	
				supplier	Organic Compounds	Dihydro-3-(tetrapropenyl)furan-2,5-dione	26544-38-7		0.041	mg	30000	232	
				supplier	Organic Compounds	Epoxy resin	Proprietary		0.041	mg	30000	232	
				supplier	Organic Compounds	Dodecylloxirane	3234-28-4		0.041	mg	30000	232	
				supplier	SVHC	Organic Compounds	Hexahydromethylphthalic anhydride	25550-51-0		0.041	mg	30000	232
				supplier	Organic Compounds	Epoxy resin modifier	Proprietary		0.041	mg	30000	232	
				supplier	Metallic compounds	Copper oxide	1317-38-0		0.007	mg	5000	39	
				supplier	Plastics/polymers	Epoxy Resin A	Proprietary		2.415	mg	21000	13549	
				supplier	Plastics/polymers	Epoxy Resin B	Proprietary		2.415	mg	21000	13549	
				supplier	Plastics/polymers	Phenol Resin	Proprietary		6.440	mg	56000	36131	
Encapsulation (EME-G631SHQ)	M-011 Other inorganic materials	115.004	mg	supplier	Glass	Silica(Amorphous)A	60676-86-0		89.755	mg	780450	503550	
				supplier	Glass	Silica(Amorphous)B	7631-86-9		13.262	mg	115320	74405	
				supplier	Non-metals	Carbon Black	1333-86-4		0.716	mg	6230	4020	
				supplier	Metals	Gold	7440-57-5		0.643	mg	1000000	3607	
				supplier	Metals	Tin	7440-31-5		1.078	mg	1000000	6048	
				supplier	Metals	Copper	7440-50-8		48.617	mg	972243	272755	
				supplier	Metals	Iron ( Fe )	7439-89-6		1.135	mg	22698	6368	
				supplier	Metals	Zinc ( Zn )	7440-66-6		0.075	mg	1500	421	
				supplier	Non-Metals	Phosphorus ( P )	7723-14-0		0.015	mg	300	84	
				supplier	Metals	Silver	7440-22-4		0.163	mg	3260	914	
Wire (Au)	Bonding Wire	0.643	mg	supplier	Metals	Gold	7440-57-5		0.643	mg	1000000	3607	
Plating Anode (Pure Tin)	M-011 Other inorganic materials	1.078	mg	supplier	Metals	Tin	7440-31-5		1.078	mg	1000000	6048	
Leadframe (C194+Ag)	Copper & its alloys	50.005	mg	supplier	Metals	Copper	7440-50-8		48.617	mg	972243	272755	
				supplier	Metals	Iron ( Fe )	7439-89-6		1.135	mg	22698	6368	
				supplier	Metals	Zinc ( Zn )	7440-66-6		0.075	mg	1500	421	
				supplier	Non-Metals	Phosphorus ( P )	7723-14-0		0.015	mg	300	84	
				supplier	Metals	Silver	7440-22-4		0.163	mg	3260	914	